

1 1. An integrated circuit socket comprising:
2 a socket housing;
3 a hinged cover secured to said housing; and
4 an infrared transmissive cap removably secured to
5 said cover.

1 2. The socket of claim 1 wherein said cap includes a
2 plurality of openings formed through the cover to allow the
3 passage of heated air.

1 3. The socket of claim 1 including spring catches on
2 opposed ends of said cap to removeably secure said cap to
3 said cover.

1 4. The socket of claim 1 wherein said cap transmits
2 at least 80 percent of incident infrared radiation.

1 5. The socket of claim 4 wherein said cap transmits
2 at least 95 percent of incident infrared radiation.

1 6. The socket of claim 1 wherein said cap is formed
2 of plastic.

1 7. The socket of claim 6 wherein said cap is formed
2 of translucent red plastic.

1 8. The socket of claim 1 wherein said cap includes
2 standoffs to space said cap from said cover.

1 9. The socket of claim 1 wherein said cap has a
2 curved lower surface.

1 10. The socket of claim 1 wherein said cap includes
2 at least two apertures and downwardly extending prongs
3 extending away from said apertures to reflect incident
4 radiation passing through said apertures.

1 11. A cap for an integrated circuit socket
2 comprising:

3 a body having apertures therethrough, said body
4 formed of a material that is infrared transmissive; and
5 tabs coupled to said body to removeably secure
6 said body to an integrated circuit socket.

1 12. The cap of claim 11 wherein said tabs include
2 spring catches on opposed ends of said cap to removeably
3 secure said cap to said socket.

1 13. The cap of claim 1 wherein said cap transmits at
2 least 80 percent of incident infrared radiation.

1 14. The cap of claim 13 wherein said cap transmits at
2 least 95 percent of incident infrared radiation.

1 15. The cap of claim 11 wherein said cap is formed of
2 plastic.

1 16. The cap of claim 15 wherein said cap is formed of
2 translucent red plastic.

1 17. The cap of claim 11 wherein said cap includes
2 standoffs to space said cap from said socket.

1 18. The cap of claim 11 wherein said cap has a curved
2 side.

1 19. The cap of claim 11 wherein said apertures
2 include downwardly extending prongs to reflect infrared
3 radiation passing through said apertures.

1 20. The cap of claim 11 wherein said cap includes
2 guides to guide said cap into alignment with said socket.

1 21. A method comprising:
2 securing an infrared transmissive cap to an
3 integrated circuit socket;

4 exposing said cap and said socket to infrared
5 energy; and
6 surface mounting said socket to a printed circuit
7 board.

1 22. The method of claim 21 including exposing said
2 cap and said socket to a surface mount reflow oven
3 producing both infrared and convective heating.

1 23. The method of claim 21 including allowing heated
2 air to circulate through said cap via apertures through
3 said cap.

1 24. The method of claim 21 including providing an
2 apertured, red plastic, infrared transmissive cap on said
3 socket.

1 25. The method of claim 21 including enabling at
2 least 80 percent of the infrared incident energy to pass
3 through said cap to said socket.